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(54) **SYSTEM, PROCESS AND A JIG FOR FORMING CONFORMAL EMI SHIELD ON PACKAGE-LEVEL ELECTRONICS OR A PORTION THEREOF**

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(57)

ABSTRACT

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A system for forming a conformal electromagnetic interference shield on at least one singulated electronic package (300), including a tray preparation module that prepares a tray (200) by mounting an electromagnetic interference tape (202) onto a frame (201), with the electromagnetic interference tape (202) covering the entirety of the frame (201), a pick and place module for placing at least one singulated electronic packages (300) onto the tray (200), a jig (100) for supporting the tray (200) having the singulated electronic packages (300), and a sputtering machine that forms a conformal electromagnetic interference shield onto the singulated electronic packages (300) through a sputtering process. The jig (100) includes a body having an arcuate surface (101), wherein the arcuate surface (101) of the jig (100) allows substantially continuous contact between the jig (100) and the electronic package (300).

